



ASE GROUP



日月光半導體 2014 第三季法人說明會

董宏思
財務長
日月光半導體
2014年10月30日



Safe Harbor Notice



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2013 Annual Report on Form 20-F filed on April 17, 2014.

合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)

營業收入淨額:

	Q3 / 2014	%	Q2 / 2014	%	季變化
封裝	32,031	48.1%	30,641	52.3%	5%
測試	6,827	10.2%	6,600	11.3%	3%
材料直接銷售	1,033	1.6%	873	1.5%	18%
電子代工服務	26,741	40.1%	20,501	35.0%	30%
其它	0	0.0%	0	0.0%	
營業收入淨額合計	66,632	100.0%	58,615	100.0%	14%
營業毛利	14,198	21.3%	12,600	21.5%	13%
營業淨利 (淨損)	8,084	12.1%	6,600	11.3%	22%
稅前淨利 (淨損)	8,590	12.9%	6,050	10.3%	42%
所得稅利益 (費用)	(1,237)	-1.9%	(818)	-1.4%	
非控制權益	(148)	-0.2%	(138)	-0.2%	
歸屬於本公司業主之淨利	7,205	10.8%	5,094	8.7%	41%
基本每股盈餘 (新台幣元)	0.94		0.66		42%
稀釋每股盈餘 (新台幣元)	0.82		0.64		28%
EBITDA	15,865	23.8%	13,109	22.4%	21%

合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q3 / 2014	%	Q3 / 2013	%	年變化
營業收入淨額:					
封裝	32,031	48.1%	29,977	52.8%	7%
測試	6,827	10.2%	6,279	11.1%	9%
材料直接銷售	1,033	1.6%	767	1.4%	35%
電子代工服務	26,741	40.1%	19,551	34.5%	37%
其它	0	0.0%	174	0.3%	
營業收入淨額合計	66,632	100.0%	56,748	100.0%	17%
營業毛利	14,198	21.3%	11,587	20.4%	23%
營業淨利 (淨損)	8,084	12.1%	6,099	10.7%	33%
稅前淨利 (淨損)	8,590	12.9%	5,368	9.5%	60%
所得稅利益 (費用)	(1,237)	-1.9%	(822)	-1.4%	
非控制權益	(148)	-0.2%	(116)	-0.2%	
歸屬於本公司業主之淨利	7,205	10.8%	4,430	7.8%	63%
基本每股盈餘 (新台幣元)	0.94		0.59		59%
稀釋每股盈餘 (新台幣元)	0.82		0.57		44%
EBITDA	15,865	23.8%	12,567	22.1%	26%

綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q3 / 2014	%	Q2 / 2014	%	季變化
營業收入淨額:					
封裝	34,349	81.4%	31,792	81.0%	8%
測試	6,827	16.2%	6,600	16.8%	3%
材料直接銷售	1,035	2.5%	874	2.2%	18%
營業收入淨額合計	42,211	100.0%	39,266	100.0%	8%
營業毛利	12,073	28.6%	10,588	27.0%	14%
營業淨利 (淨損)	7,348	17.4%	5,973	15.2%	23%
稅前淨利 (淨損)	8,366	19.8%	5,779	14.7%	45%
所得稅利益 (費用)	(1,105)	-2.6%	(647)	-1.6%	
非控制權益	(56)	-0.1%	(38)	-0.1%	
歸屬於本公司業主之淨利	7,205	17.1%	5,094	13.0%	41%
稀釋每股盈餘 (新台幣元)	0.82		0.64		28%
EBITDA	14,748	34.9%	12,055	30.7%	22%

綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)

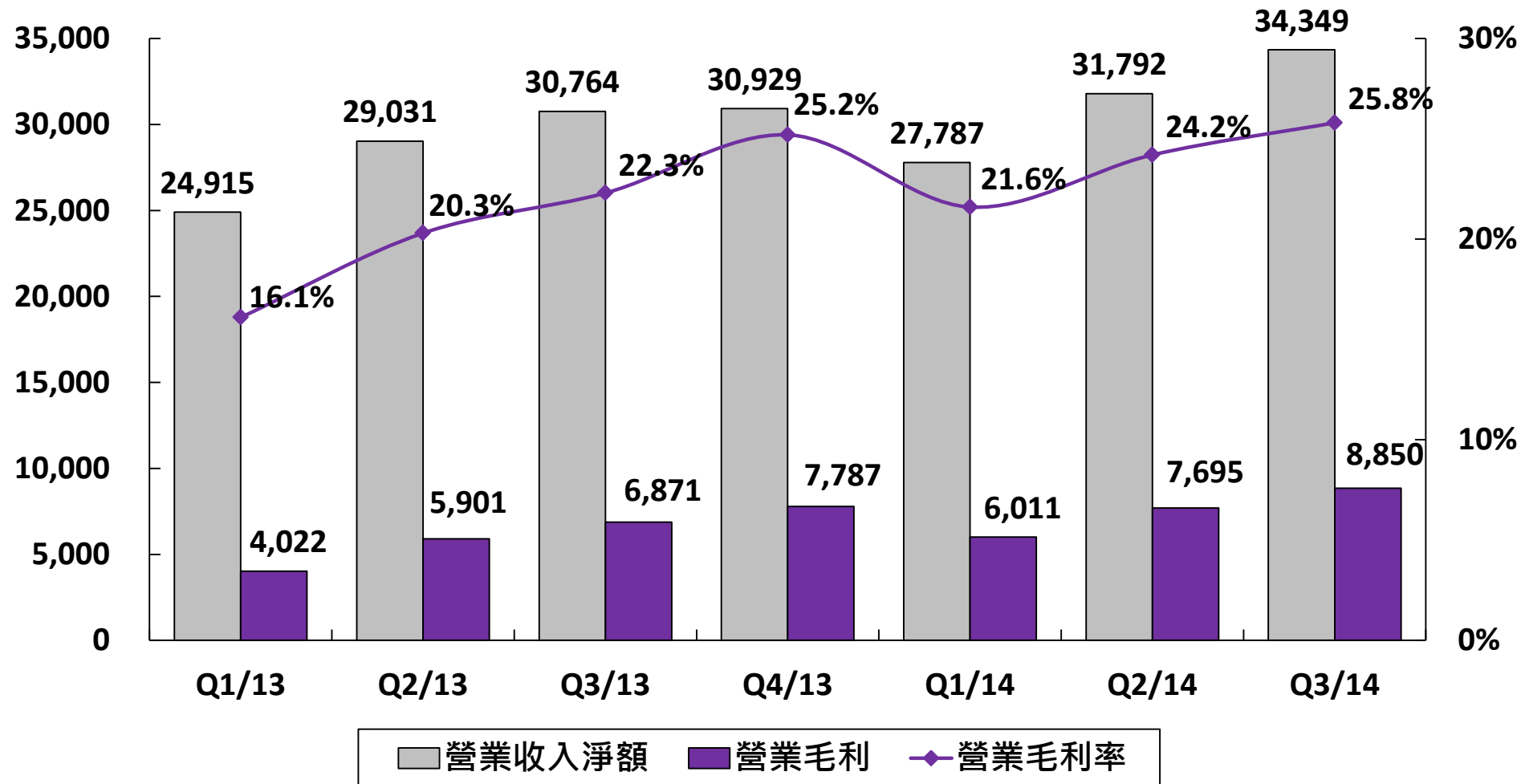


(新台幣百萬元)	Q3 / 2014	%	Q3 / 2013	%	年變化
營業收入淨額:					
封裝	34,349	81.4%	30,764	81.4%	12%
測試	6,827	16.2%	6,279	16.6%	9%
材料直接銷售	1,035	2.5%	767	2.0%	35%
營業收入淨額合計	42,211	100.0%	37,810	100.0%	12%
營業毛利	12,073	28.6%	9,646	25.5%	25%
營業淨利 (淨損)	7,348	17.4%	5,383	14.2%	37%
稅前淨利 (淨損)	8,366	19.8%	5,134	13.6%	63%
所得稅利益 (費用)	(1,105)	-2.6%	(661)	-1.7%	
非控制權益	(56)	-0.1%	(43)	-0.1%	
歸屬於本公司業主之淨利	7,205	17.1%	4,430	11.7%	63%
稀釋每股盈餘 (新台幣元)	0.82		0.57		44%
EBITDA	14,748	34.9%	11,371	30.1%	30%

封裝業務

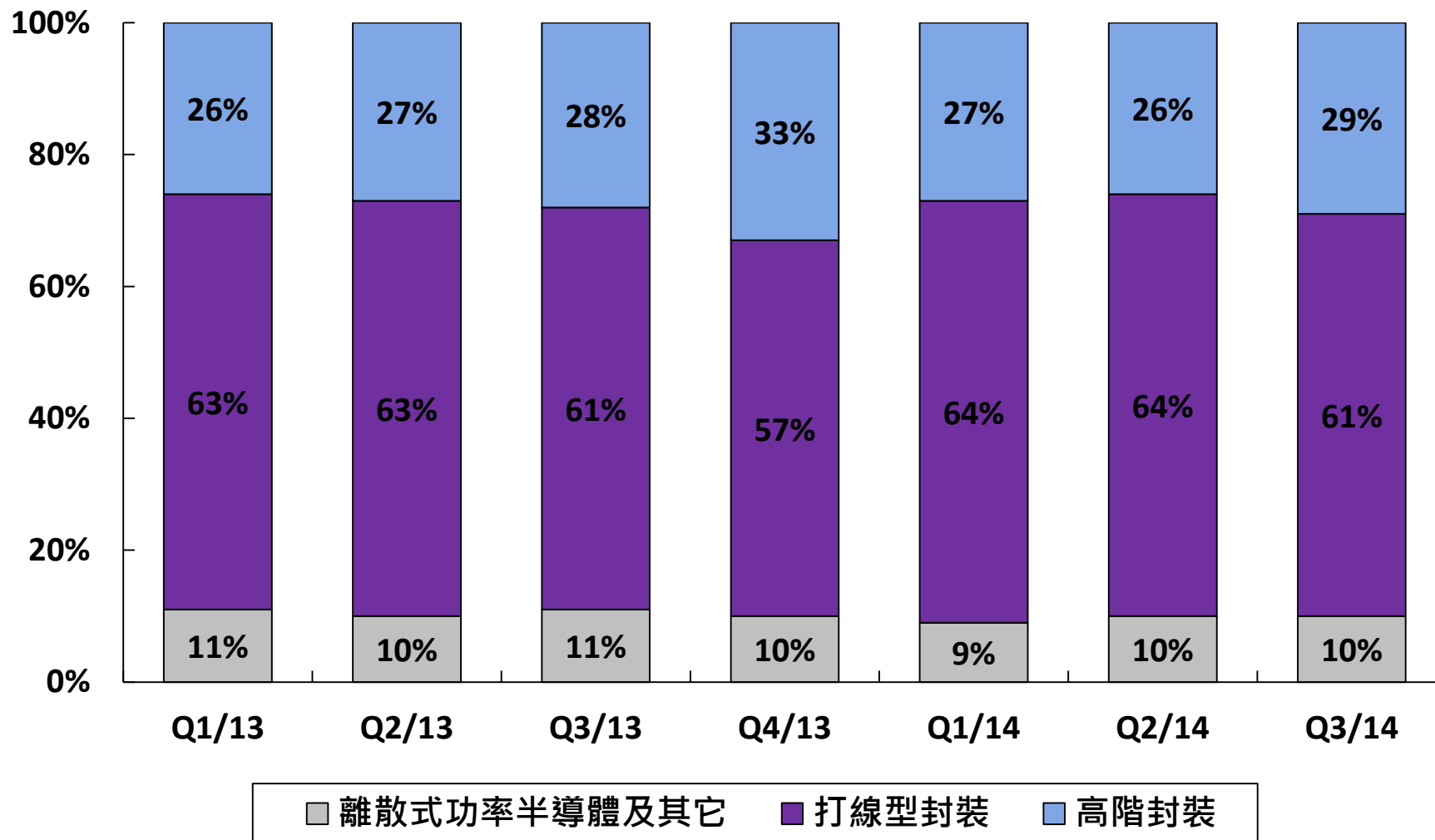


新台幣百萬元



封裝業務

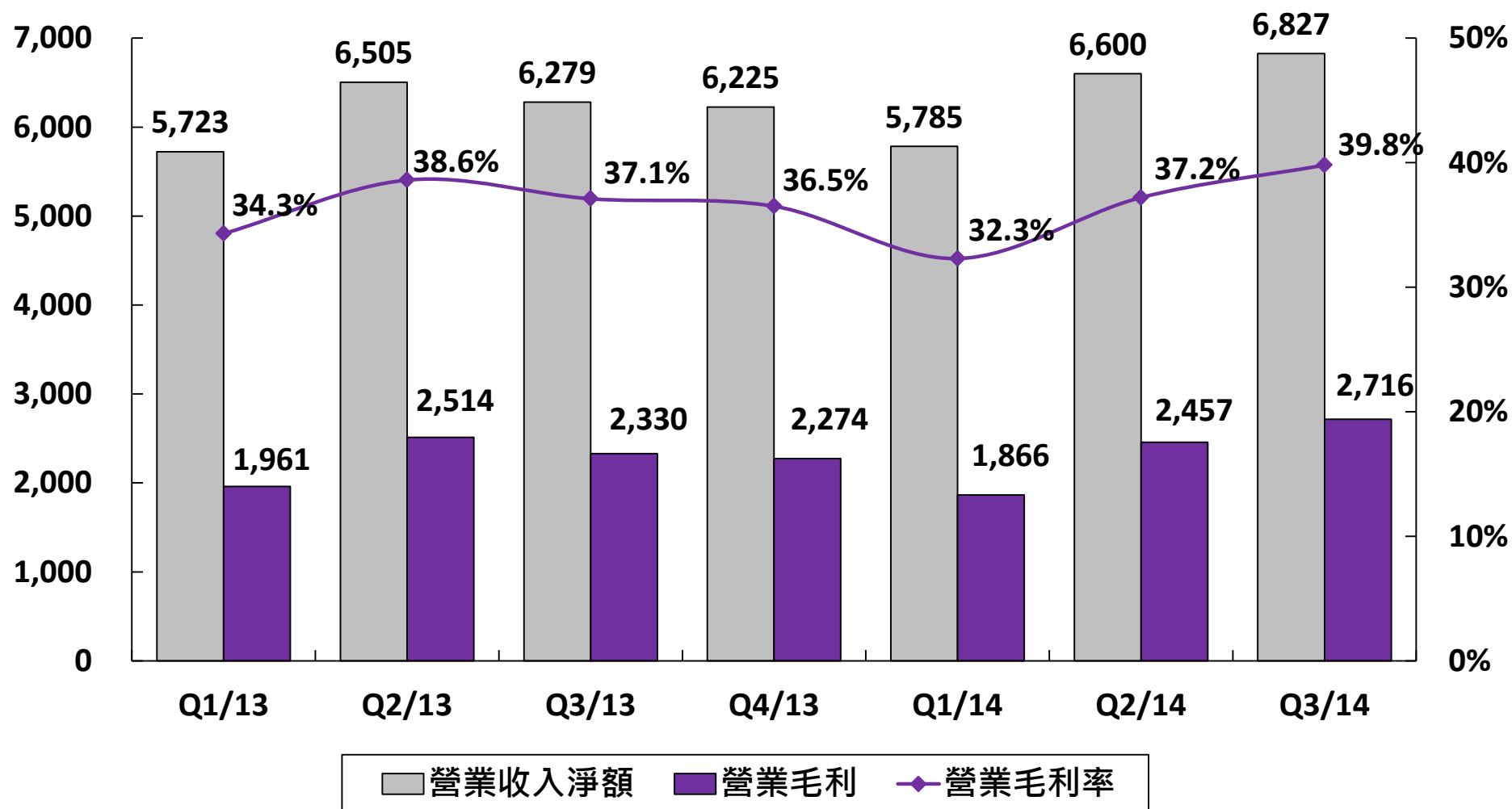
產品組合



測試業務



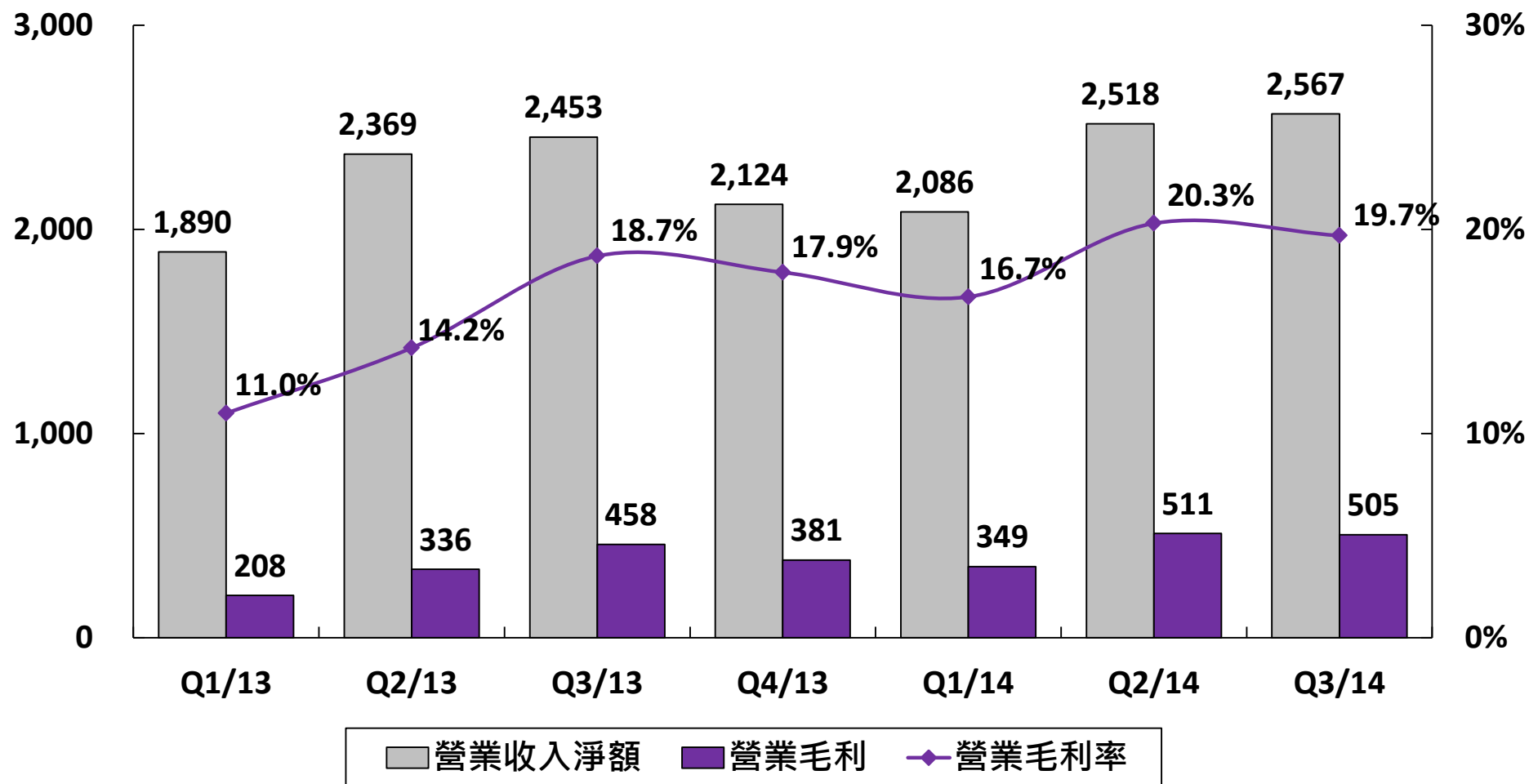
新台幣百萬元



材料業務



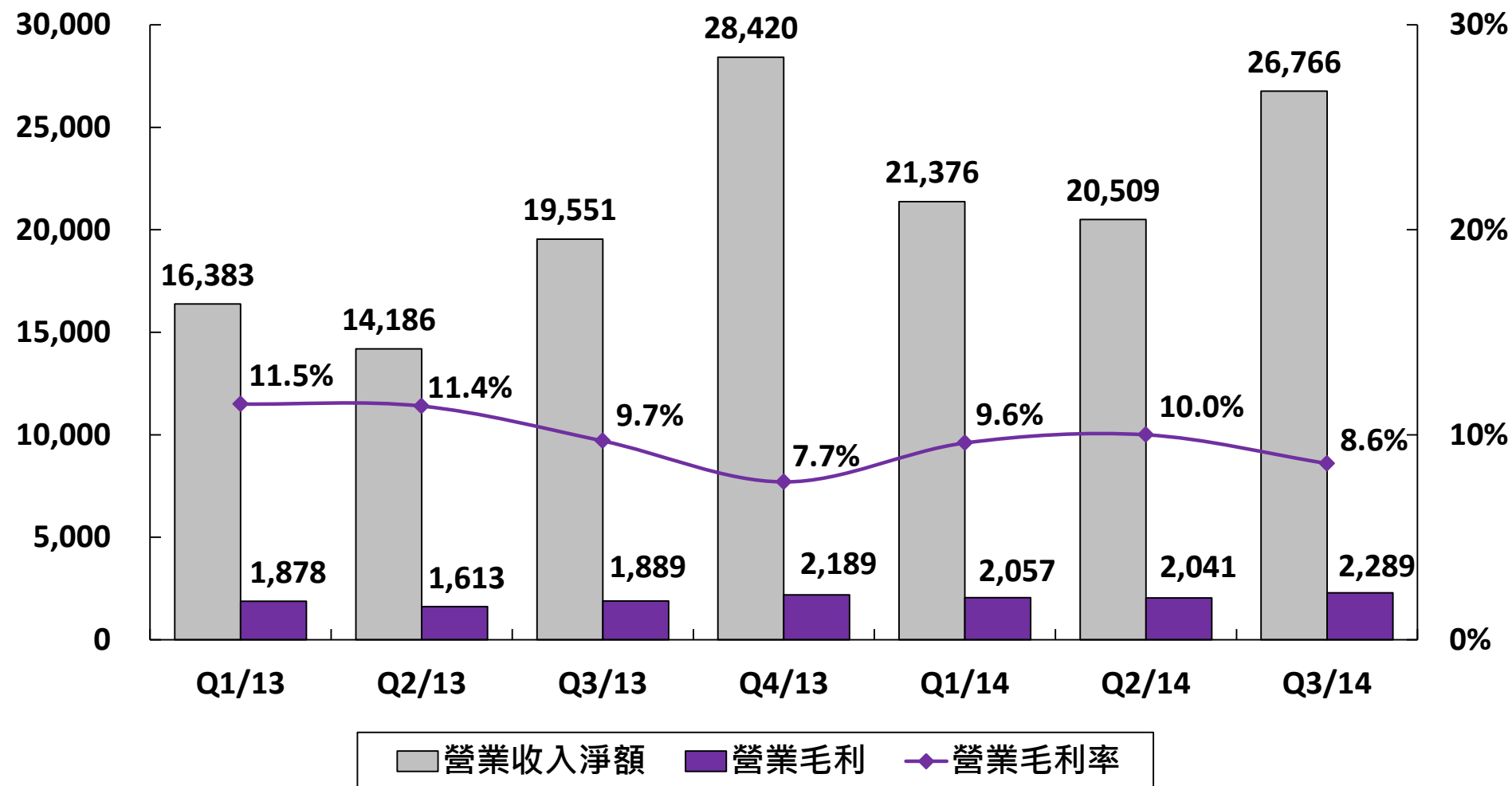
新台幣百萬元



電子代工服務業務

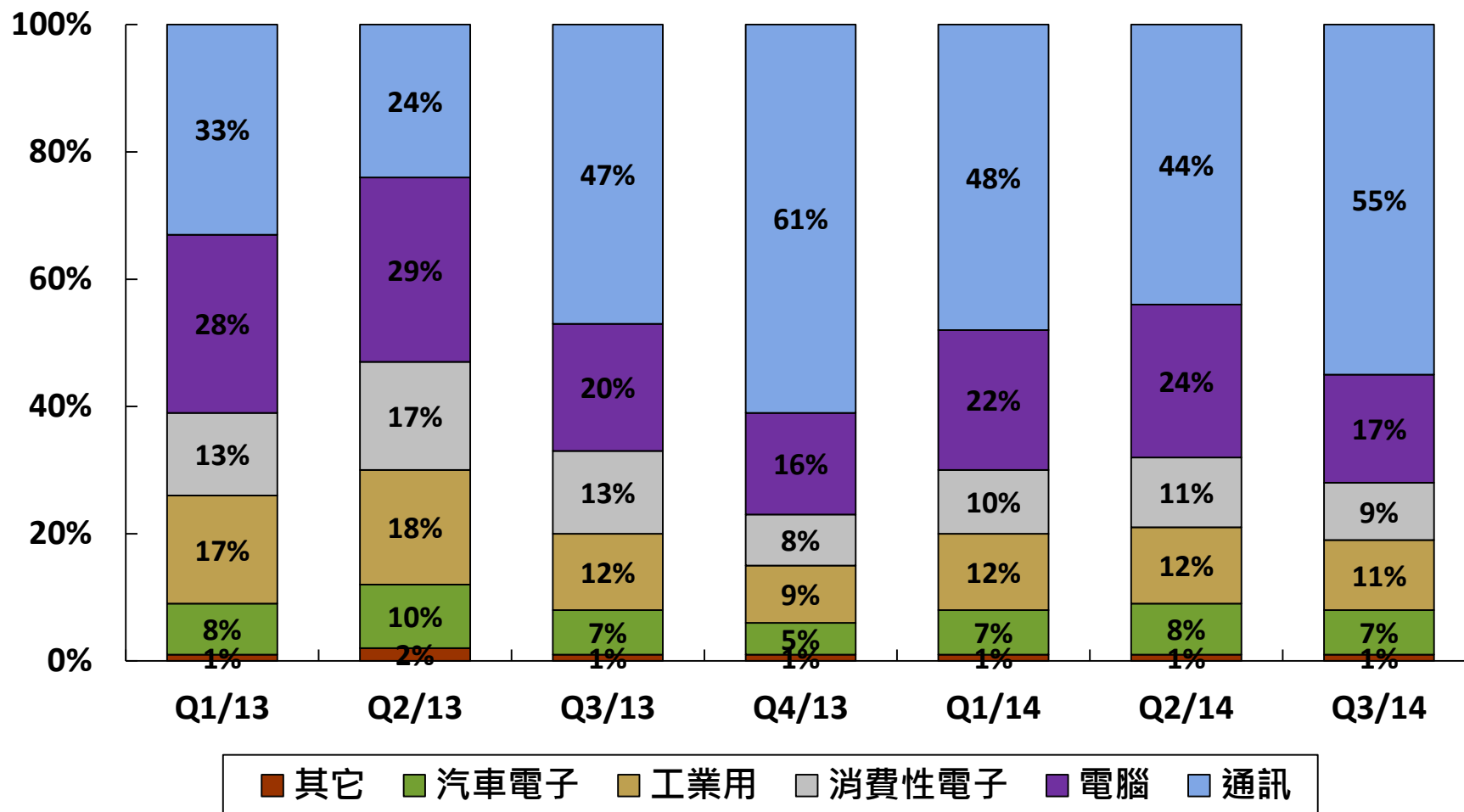


新台幣百萬元



電子代工服務業務

產品應用別



資產負債表及重要財務指標

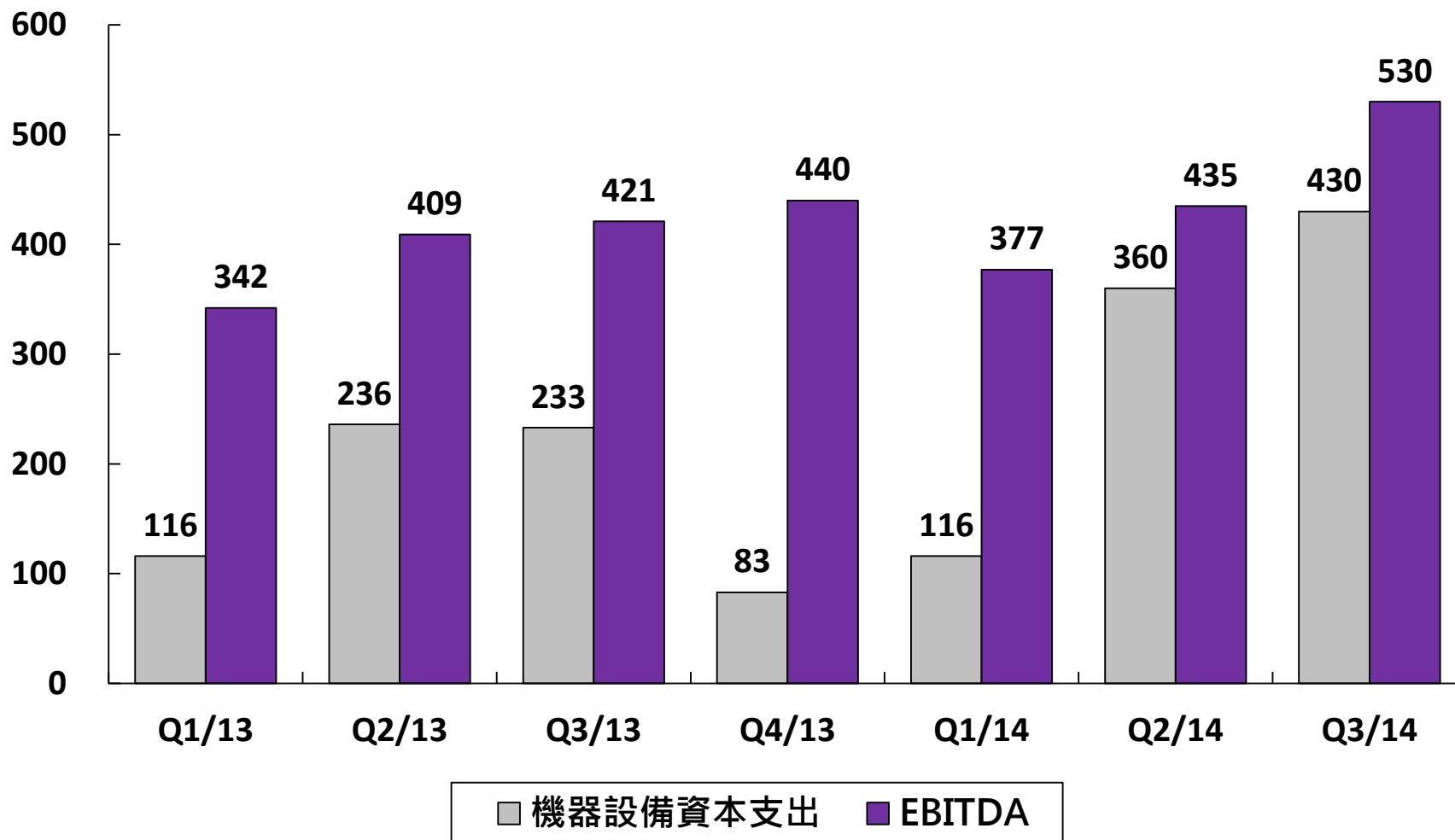
(未經會計師查核)



(新台幣百萬元)	2014年9月30日	2014年6月30日	季變化
現金及約當現金	32,968	41,730	-21.0%
金融資產 - 流動	3,817	3,653	4.5%
金融資產 - 非流動及採用權益法之投資	2,475	2,574	-3.8%
不動產、廠房及設備	148,998	135,555	9.9%
資產總計	304,727	287,600	6.0%
短期借款	38,672	33,281	16.2%
一年內到期之應付公司債	0	728	
一年內到期之長期借款及應付租賃款	3,226	5,316	-39.3%
應付公司債	30,194	20,781	45.3%
長期借款及應付租賃款	22,826	26,940	-15.3%
權益總計 (含非控制權益)	136,111	126,876	7.3%
當季 EBITDA	15,865	13,109	21.0%
流動比率	1.25	1.23	
負債權益比率	0.43	0.33	

機器設備資本支出及EBITDA

美金百萬元

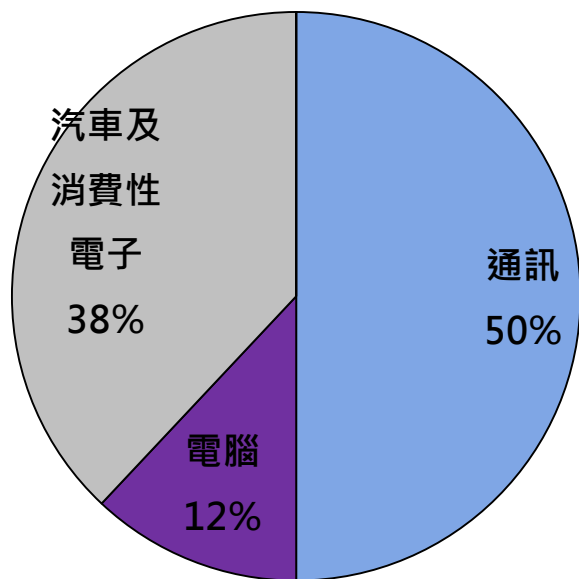


半導體封測營收

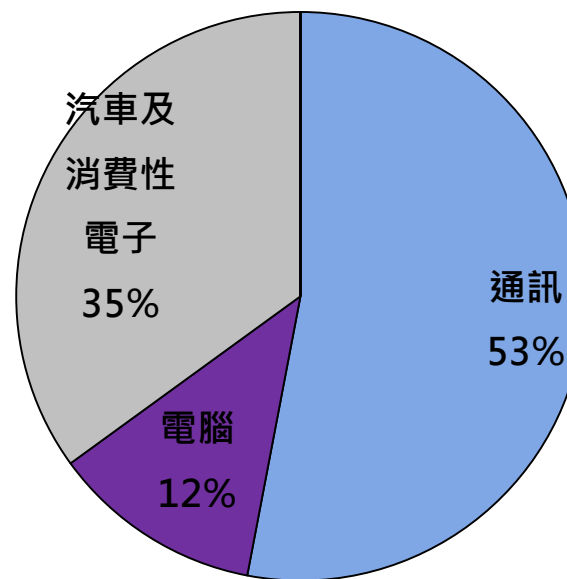
產品應用別佔比



Q2/2014



Q3/2014



2014年第四季業績展望



根據對當前業務狀況的評估及匯率的假設，日月光公司2014年第四季的業績展望如下：

- 半導體封測事業之整體產能將微幅增加大約1%，整體產能利用率將由第三季的水準增加大約1-3%；
- 電子代工服務第四季營運狀況將延續第三季之季成長趨勢；
- 合併營業毛利率將小幅度下滑，而合併營業淨利率將持平。

Thank You

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